

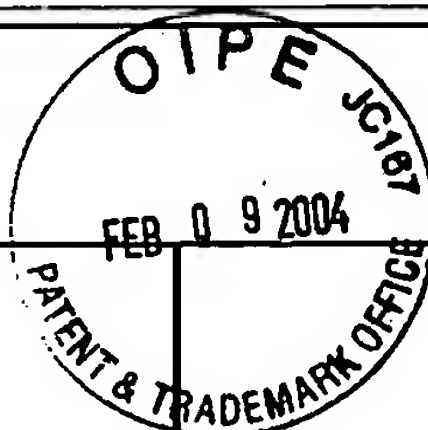
**Change Of Attorney Or Agent's Address In Application
(37 CFR 1.8(a))**

Docket No.
END920030014US1

In Re Application Of: **R. J. Stutzman et al.**

Serial No.
10/634,554

Filing Date
08/05/2003



Examiner
N/A

Group Art Unit
2835

Invention: **FLIP CHIP PACKAGE WITH HEAT SPREADER ALLOWING MULTIPLE HEAT SINK
ATTACHMENT**

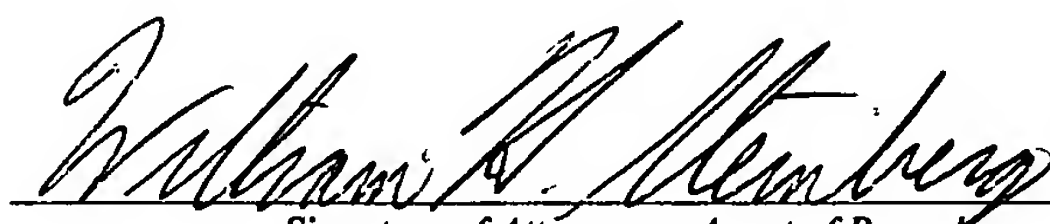
TO THE COMMISSIONER FOR PATENTS

Please send all correspondence for this application to:

**John A. Jordan
11 Hyspot Road
Greenfield Center, NY 12833**

Please direct all telephone calls to:

John A. Jordan, (518) 587-1902


Signature of Attorney or Agent of Record

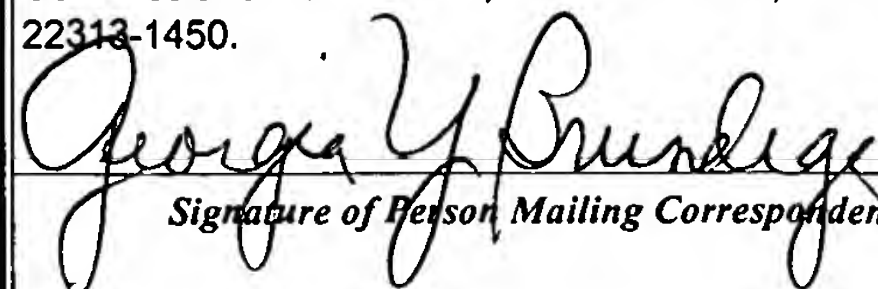
Dated:

2/4/04

**William H. Steinberg, Reg. No. 28,540
IBM Corporation / IP Law Dept. IQ0A, Bldg. 040-3
1701 North Street
Endicott, NY 13760
Telephone: (607) 429-3979
Fax No.: (607) 429-4119**

Registration Number & Address of Attorney or Agent of Record

I certify that this document is being deposited on
2/05/04 with the U.S. Postal Service as first
class mail under 37 C.F.R. 1.8 and is addressed to the
Commissioner for Patents, P.O. Box 1450, Alexandria, VA
22313-1450.



Signature of Person Mailing Correspondence

Georgia Y. Brundage

Typed or Printed Name of Person Mailing Correspondence